PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JOHN D. BRAZZLE	09/12/2018
FREDERICK E. BEVILLE	08/20/2018
DAVID R. NG	08/16/2018
MICHAEL J. ANDERSON	09/19/2018
YUCHENG YING	08/21/2018

RECEIVING PARTY DATA

Name:	LINEAR TECHNOLOGY HOLDING LLC
Street Address:	ONE TECHNOLOGY WAY
City:	NORWOOD
State/Country:	MASSACHUSETTS
Postal Code:	02062

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16152182

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	P00745US02
NAME OF SUBMITTER:	BRIAN D. OGONOWSKY
SIGNATURE:	/Brian D Ogonowsky/
DATE SIGNED:	10/04/2018

Total Attachments: 6
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ASSIGNMENT

WHEREAS, I am a named inventor with residence as listed below, having invented certain new and useful improvements as described in an application for United States Letters Patent entitled "STACKED CIRCUIT PACKAGE WITH MOLDED BASE HAVING LASER DRILLED OPENINGS FOR UPPER PACKAGE," (hereinafter referred to as "Application") and having internal reference number of P00745US02;

WHEREAS, I hereby authorize and request the attorneys or agents associated with United States Patent and Trademark Office Customer No. 122912 to insert here in parentheses (Ser. No. 16/152,182; Filing Date: 2018-10-04) the filing date and serial number of the Application when known;

WHEREAS, Linear Technology Holding LLC (hereinafter referred to as "Assignee"), a Delaware Corporation, with an address of One Technology Way, Norwood, MA 02062, desires to acquire my entire right, title and interest in and to any and all inventions and improvements that are disclosed in the Application (hereinafter referred to as "Invention"), including any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I hereby assign and transfer, and hereby agree to assign and transfer, to Assignee, all right, title and interest in and to the Invention and in and to the Application and all patents which may be granted therefrom, and all related applications (e.g., provisional applications, divisional applications, reissues, reexaminations, continuation applications, continuation-in-part applications, extensions thereof, design applications, applications in foreign countries, international applications, national phase applications, and the like). I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents, for the Invention, or patents resulting therefrom, insofar as my interest is concerned, to Assignee.

I also hereby assign and transfer, and hereby agree to assign and transfer to Assignee, all right, title and interest to the Invention, the Application or any related application throughout the world, including all rights of priority resulting from the filing of the Application or any related application, including but not limited to: the right to file applications and obtain patents, utility models, industrial models and designs for the Invention in Assignee's own name throughout the world, the right to claim priority from the Application or any related application when filing applications and obtaining patents, utility models, industrial models and designs for the Invention throughout the world, and all rights to publish cautionary notices reserving ownership of the Invention and all rights to register the Invention in appropriate registries. I further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such right, title and interest in and to Assignee.

I will communicate to Assignee any facts known to me respecting any improvements to the Invention; and I will sign all lawful papers, execute all rightful assignments, execute all provisional, divisional, continuation, continuation-in-part, reissue and substitute applications, make lawful oaths and declarations, and generally do everything possible to vest title in and to Assignee and to aid Assignee to obtain and enforce proper protection for the Invention in all countries and jurisdictions throughout the world. I irrevocably appoint Analog Devices, Inc. as my attorney-in-fact to execute on my behalf any documents deemed necessary by Analog Devices, Inc. to obtain and enforce proper protection for the Invention in all countries and jurisdictions throughout the world. I agree to testify and cooperate with Assignee in any judicial proceeding, administrative proceeding, post-grant proceeding, or other proceeding concerning the Invention (including litigation with a third party over any patent issued on the Invention), and Assignee agrees to cover my reasonable costs and expenses (if any).

This Assignment shall be binding on the parties' successors, assigns and legal representatives.

Title of Invention: STACKED CIRCUIT PACKAGE WITH MOLDED BASE HAVING LASER DRILLED OPENINGS FOR UPPER PACKAGE

Full name of inventor: John D. Brazzle

Inventor's signature:

Date: 9/12/2018

Inventor Home Address: 1581 Biarritz St.
Tracy, CA 95304

Witness's Print Name: Michael Anderson

Witness's signature:

Witness Home Address: 1790 White Oaks Rd
Campbell CA 95008

ATTORNEY DOCKET NO.
P00745US02

ASSIGNMENT

Title of Invention: STACKED CIRCUIT PACKAGE WITH MOLDED BASE HAVING LASER DRILLED OPENINGS FOR UPPER PACKAGE

Full name of inventor: Frederick E. Beville

Inventor's signature: Frederick E. Beville

Date: 8/20/18

Inventor Home Address: 14639 Berry Way
San Jose, CA 95124

Witness's Print Name: John D. Brazak

Witness's signature:

Witness Home Address: 1581 Burritz St.
Tracy CA. 95304

Title of Invention: STACKED CIRCUIT PACKAGE WITH MOLDED BASE HAVING LASER DRILLED OPENINGS FOR UPPER PACKAGE

Full name of inventor: David R. Ng

Inventor's signature: David R Ng

Date: 8/16/18

Inventor Home Address: 4749 Bannock Circle
San Jose, CA 95130

Witness's Print Name: Eugene Cheung

Witness's signature:

Witness Home Address: 45555 Kiowa Ct
Fremont CA 94539

ATTORNEY DOCKET NO.
P00745US02

ASSIGNMENT

Title of Invention: STACKED CIRCUIT PACKAGE WITH MOLDED BASE HAVING LASER DRILLED OPENINGS FOR UPPER PACKAGE

Full name of inventor: Michael J. Anderson

Inventor's signature:

Date: 9/19/18

Inventor Home Address: 1790 White Oaks Rd
Campbell CA 95008

Witness's Print Name: John P. Brazzle

Witness's signature:

Witness Home Address: 1581 Biarritz St.
Tracy, CA 95304

Title of Invention: STACKED CIRCUIT PACKAGE WITH MOLDED BASE HAVING LASER DRILLED OPENINGS FOR UPPER PACKAGE

Full name of inventor: Yucheng Ying

Inventor's signature:

Date: 8/21/18

Inventor Home Address: 8208 Lillian Way
San Jose, CA 95120

Witness's Print Name: John D. Blazzle

Witness's signature:

Witness Home Address: 1581 Biarritz St.
Tracy, CA. 95304